

■ Notice (Soldering and Mounting)

1.1. Soldering Condition

(1) Reflow

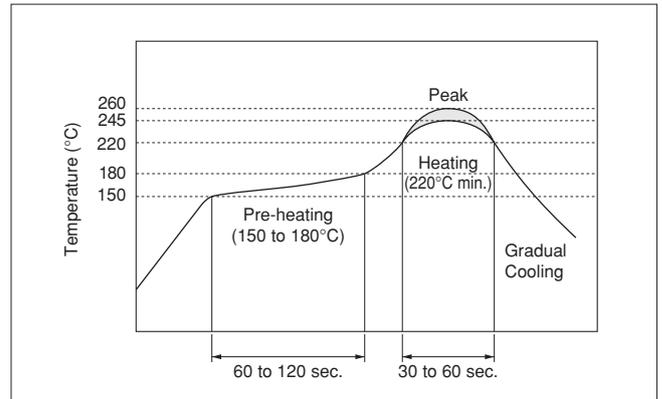
Please mount components on a circuit board by the re-flow soldering.

Flux: Please use rosin based flux, but do not use water soluble flux.

Solder: Please use solder (Sn-3.0Ag-0.5Cu) under the following condition.

Standard thickness of soldering paste: 0.10 to 0.15mm

	Condition	
Pre-heating	150 to 180°C	60 to 120 sec.
Heating	220°C min.	30 to 60 sec.
Peak Temperature	245°C min. 260°C max. 5 sec. max.	



(2) Soldering Iron

If compelled to mount the component by using soldering iron, please do not directly touch the component with the soldering iron. The component terminals or electrical characteristics may be damaged if excessive thermal stress is applied.

	Condition
Pre-heating	150°C 60 sec.
Heating of the Soldering Iron	350°C max.
Watt	30W max.
Shape of the Soldering Iron	ø3mm max.
Soldering Time	5 sec. max.
Solder	Sn-3.0Ag-0.5Cu

1.2. Optimum Solder Amount for Soldering

Please make the solder volume below the height of the substrate. When exceeding the substrate, the damage of sealing part between the metal cap and the substrate may occur.

1.3. Others

Do not reuse components once mounted onto a circuit board.

2. Wash

The component cannot withstand washing.

3. Notice for Mounting

The component is recommended with placement machines employing optical placement capabilities.

The component might be damaged by mechanical force depending on placement machine and condition.

Make sure that you have evaluated by using placement machines before going into mass production.

Do not use placement machines employing mechanical positioning.

Please contact Murata for details beforehand.

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■ Notice (Storage and Operating Condition)

1. Product Storage Condition

Please store the products in room where the temperature/humidity is stable. And avoid such places where there are large temperature changes. Please store the products under the following conditions:

Temperature: -10 to + 40 degrees C

Humidity: 15 to 85% R.H.

2. Expire Date on Storage

Expire date (Shelf life) of the products is six months after delivery under the conditions of a sealed and an unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because the products may be degraded in the solderability and/or rusty. Please confirm solderability and characteristics for the products regularly.

3. Notice on Product Storage

- (1) Please do not store the products in a chemical atmosphere (Acids, Alkali, Bases, Organic gas, Sulfides and so on), because the characteristics may be reduced in quality, and/or be degraded in the solderability due to the storage in a chemical atmosphere.

- (2) Please do not put the products directly on the floor without anything under them to avoid damp places and/or dusty places.
- (3) Please do not store the products in the places such as: in a damp heated place, in a place where direct sunlight comes in, in place applying vibrations.
- (4) Please use the products immediately after the package is opened, because the characteristics may be reduced in quality, and/or be degraded in the solderability due to storage under the poor condition.
- (5) Please do not drop the products to avoid cracking of crystal element.

4. Others

Conformal coating or washing of the component is not acceptable because it is not hermetically sealed. Please be sure to consult with our sales representative or engineer whenever and prior to using the products.

■ Notice (Rating)

The component may be damaged if excess mechanical stress is applied.

■ Notice (Handling)

1. Irregular or stop oscillation may occur under unmatched circuit conditions.

Please design your oscillation circuit to get 5 times or more of a negative resistance against the maximum value of the Equivalent Series Resistance, that is specified in order.

2. Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product.